L Numb r	Hits	S arch Text	DB	Time stamp
Anin I	23	( miconduct rand (package rpackaging	USPAT;	2002/12/10
		r packaged) and (stack or stacking or	US-PGPUB;	11:33
		stacked) and (offset or off-set or offsetting	EPO; JPO;	
		or off-setting or stagger or staggered or	DERWENT;	
		staggering)).clm.	IBM_TDB	
•	2	((semiconductor and (package or packaging	USPAT;	2002/12/10
		or packaged) and (stack or stacking or	US-PGPUB;	11:33
		stacked) and (offset or off-set or offsetting	EPO; JPO;	
		or off-setting or stagger or staggered or	DERWENT;	
		staggering)).clm.) and flash and density	IBM_TDB	
_	861	package near5 (offset or off-set or	USPAT;	2002/12/10
		offsetting or off-setting or stagger or	US-PGPUB;	11:34
		staggered or staggering)	EPO; JPO;	
		33	DERWENT:	
			IBM TDB	
-	1110	(package or packaged or packaging) near5	USPAT;	2002/12/10
		(offset or off-set or offsetting or off-setting	US-PGPUB;	13:30
	İ	or stagger or staggered or staggering)	EPO; JPO;	
		33 33	DERWENT;	
	i		IBM TDB	ĺ
-	32	((package or packaged or packaging) near5	USPAT;	2002/12/10
		(offset or off-set or offsetting or off-setting	US-PGPUB;	11:36
		or stagger or staggered or staggering)) and	EPO; JPO;	
		(flash and density)	DERWENT:	
		(inden and achieffy)	IBM_TDB	
-	933	(die or package or packaging) near2 (offset	USPAT;	2002/12/10
	-	or off-set)	US-PGPUB;	13:33
			EPO; JPO;	
:			DERWENT;	
			IBM_TDB	
-	408	((die or package or packaging) near2 (offset	USPAT;	2002/12/10
		or off-set)).ti,ab,clm.	US-PGPUB;	13:36
		,	EPO; JPO;	
			DERWENT;	
	!		IBM_TDB	1
_	0	(((die or package or packaging) near2	USPAT;	2002/12/10
		(offset or off-set)).ti,ab,clm.) and (stack or	US-PGPUB;	13:34
		stacked or stacking) and semiconductor	EPO; JPO;	1
		and flash and density and (memory or	DERWENT;	
		storage)	IBM_TDB	
-	55	(((die or package or packaging) near2	USPAT;	2002/12/10
		(offset or off-set)).ti,ab,clm.) and (stack or	US-PGPUB;	13:35
		stacked or stacking or stackable)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	30	(((die or package or packaging) near2	USPAT;	2002/12/10
		(offs t or off-set)).ti,ab,clm.) and ( tack or	US-PGPUB;	13:35
		tacked or stacking r stackabl ).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	1

•	6	((((di rpackag rpackaging) near2	USPAT;	2002/12/10
		(offset roff-set)).ti,ab,clm.) and (stack or	US-PGPUB;	13:36
		sta ked r stacking or	EPO; JPO;	
		sta kabl ).ti,ab,clm.) and (memory or	DERWENT;	
		storage)	IBM_TDB	
-	20	((((die or package or packaging) near2	USPAT;	2002/12/10
		(offset or off-set)).ti,ab,clm.) and	US-PGPUB;	13:37
		semiconductor) and (memory or storage)	EPO; JPO;	
		· · · · · · · · · · · · · · · · · · ·	DERWENT;	
			IBM_TDB	
-	77	(((die or package or packaging) near2	USPAT;	2002/12/10
		(offset or off-set)).ti,ab,clm.) and	US-PGPUB;	13:41
		semiconductor	EPO; JPO;	
	}		DERWENT;	
			IBM_TDB	